

GSTMMBT3906TFF

PNP General Purpose Transistor

Product Description

This device is designed as a general purpose amplifier and switch.

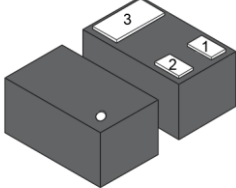
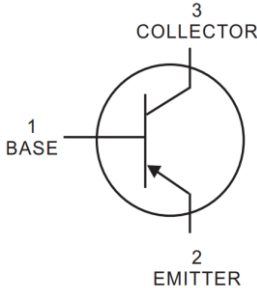
Features

- Complementary to GSTMMBT3904
- Collector-emitter voltage $V_{CE} = -40V$
- Collector current $I_C = -200mA$
- RoHS Compliant and Halogen Free

Mechanical Data

- DFN1006-3L package design
- Epoxy meets UL 94 V-0 Flammability Rating

Packages & Pin Assignments

DFN1006-3L		Equivalent Circuit
		
Pin	Description	
1	Base	
2	Emitter	
3	Collector	

Ordering and Marking Information

Ordering Information				
Part Number	Package	h _{FE} Range	Marking Code	Quantity/Reel
GSTMMBT3906TFF	DFN1006-3L	*100-300	3N	10,000 PCS
GSTMMBT3906 1 2				
- Product Code: GSTMMBT3906		- Package Code: 1 is TF for DFN1006-3L		- Green Level: F for RoHS Compliant and Halogen Free
Marking Information				
3N				
- Product Code: 3N				

* $I_C = -10mA$, $V_{CE} = -1.0V$

Absolute Maximum Ratings (T_A=25°C unless otherwise noted)

Symbol	Parameter	Value	Unit
V _{CEO}	Collector-Emitter Voltage	-40	V
V _{CBO}	Collector-Base Voltage	-40	V
V _{EBO}	Emitter-Base Voltage	-5	V
I _C	Collector Current	-200	mA
P _D	Power Dissipation T _A =25°C*	100	mW
R _{ΘJA}	Thermal Resistance, Junction to Ambient	1250	°C/W
T _J	Junction Temperature Range	150	°C
T _{STG}	Storage Temperature Range	-55 to +150	°C

* Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

Electrical Characteristics (T_A=25°C unless otherwise specified)

Symbol	Description	Conditions	Min	Max	Unit
V _{(BR)CEO}	Collector-Emitter Breakdown Voltage	I _C =-1mA, I _B =0mA	-40	-	V
V _{(BR)CBO}	Collector-Base Breakdown Voltage	I _C =-0.01mA, I _E =0mA	-40	-	V
V _{(BR)EBO}	Emitter-Base Breakdown Voltage	I _E =-0.01mA, I _C =0mA	-5.0	-	V
I _{CEX}	Collector Cutoff Current	V _{CE} =-30V, V _{EB} =-3V	-	-50	nA
I _{EBO}	Emitter Cutoff Current	V _{EB} =-5V, I _C =0mA	-	-100	nA
h _{FE}	DC Current Gain	I _C =-0.1mA, V _{CE} =-1.0V	60	-	-
		I _C =-1mA, V _{CE} =-1.0V	80	-	-
		I _C =-10mA, V _{CE} =-1.0V	100	300	-
		I _C =-50mA, V _{CE} =-1.0V	60	-	-
		I _C =-100mA, V _{CE} =-1.0V	30	-	-
V _{CE(sat)}	Collector-Emitter Saturation Voltage	I _C =-10mA, I _B =-1mA	-	-0.25	V
		I _C =-50mA, I _B =-5mA	-	-0.40	V
V _{BE(sat)}	Base-Emitter Saturation Voltage	I _C =-10mA, I _B =-1mA	-0.65	-0.85	V
		I _C =-50mA, I _B =-5mA	-	-0.95	V
f _T	Current Gain-Bandwidth Product	V _{CE} =-20V, I _C =-10mA, f=100MHz	250	-	MHz
C _{ob}	Collector Output Capacitance	V _{CB} =-5.0V, I _E =0, f=1.0MHz	-	4.5	pF
C _{ib}	Base Input Capacitance	V _{EB} =-0.5V, I _E =0, f=1.0MHz	-	10	pF
t _d	Delay Time	V _{CC} =-3V, I _C =-10mA, I _{B1} =-1mA	-	35	ns
t _r	Rise Time	V _{CC} =-3V, I _C =-10mA, I _{B1} =-1mA	-	35	ns
t _s	Storage Time	V _{CC} =-30V, I _C =-10mA, I _{B1} =I _{B2} =-1mA	-	225	ns
t _f	Fall Time	V _{CC} =-30V, I _C =-10mA, I _{B1} =I _{B2} =-1mA	-	75	ns

Typical Performance Characteristics ($T_A=25^\circ\text{C}$ unless otherwise specified)

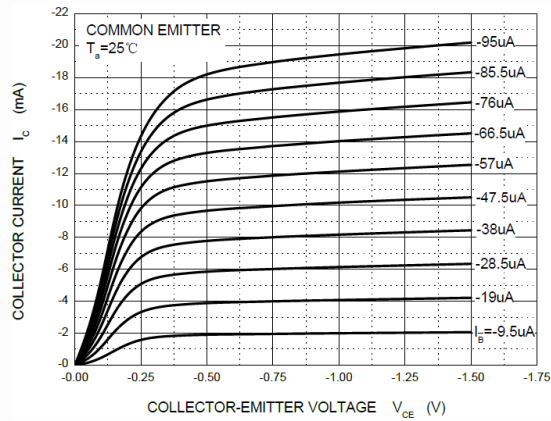


Figure 1. Static Characteristic

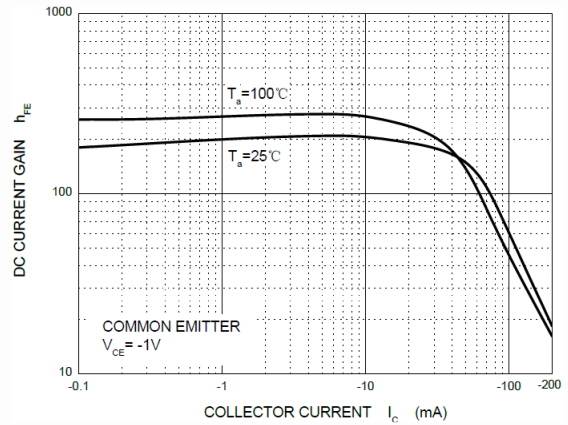


Figure 2. Typical h_{FE} vs. Collector Current

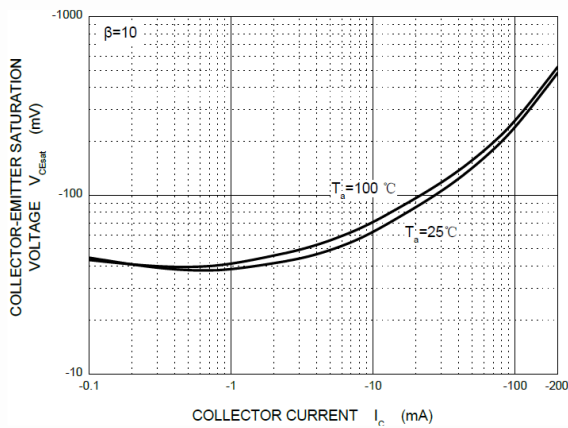


Figure 3. Typical $V_{CE(sat)}$ vs. Collector Current

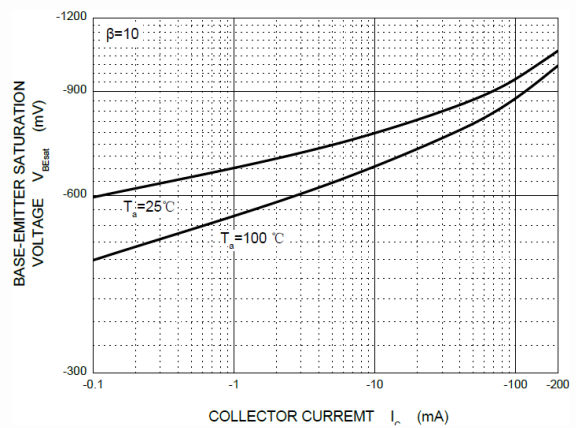


Figure 4. Typical $V_{BE(sat)}$ vs. Collector Current

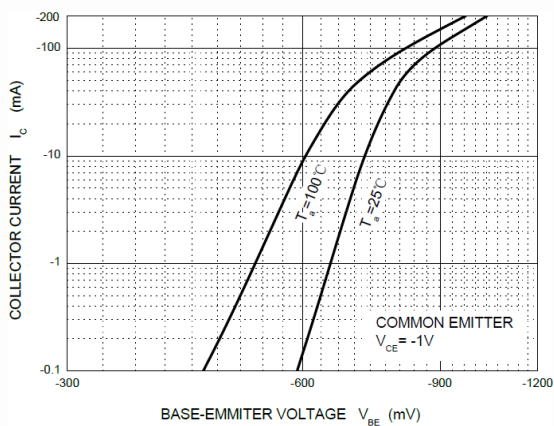


Figure 5. Typical Collector Current vs. Collector-Emitter Voltage

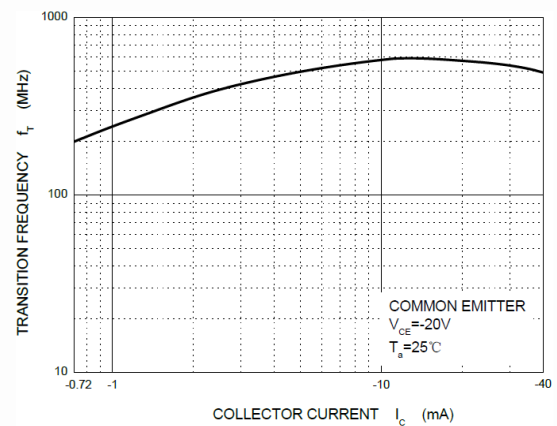


Figure 6. Transition Frequency vs. Collector Current

Typical Performance Characteristics (Continued)

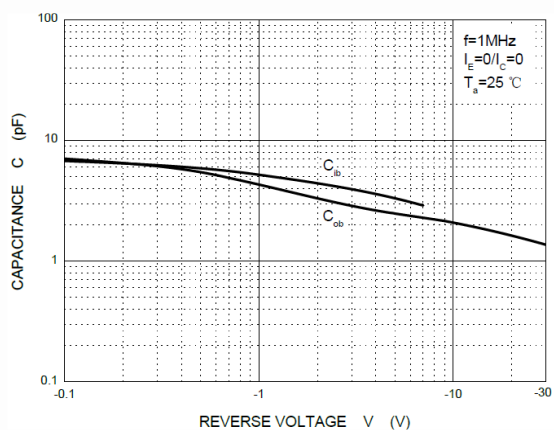


Figure 7. Typical Capacitance Characteristics

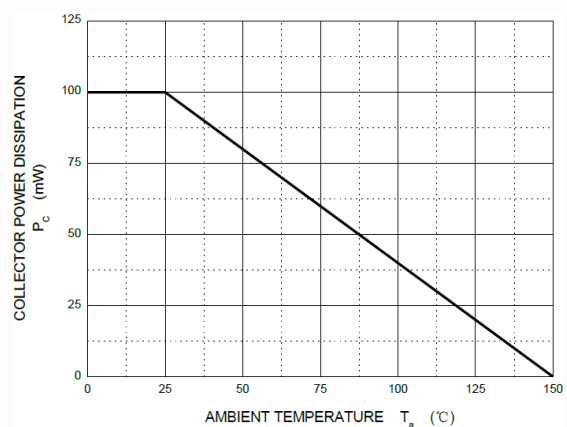
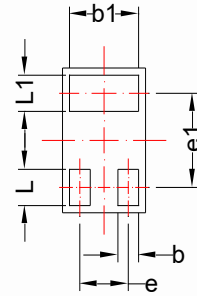
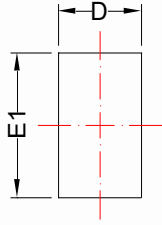


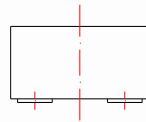
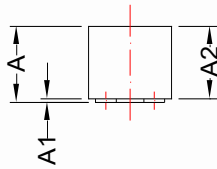
Figure 8. Power Dissipation vs. Ambient Temperature

DFN1006-3L

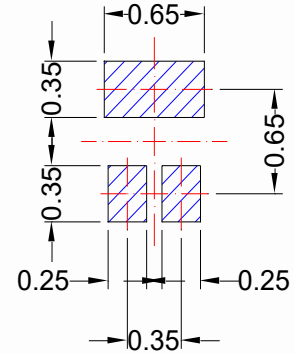
Package Dimension



BACKSIDE VIEW



Recommended Land Pattern



Unit: mm

Dimensions

Symbol	Millimeters		Inches	
	Min	Max	Min	Max
A	0.45	0.55	0.018	0.022
A1	0.00	0.05	0.000	0.002
b	0.45	0.55	0.018	0.022
b1	0.1	0.20	0.004	0.008
C	0.12	0.18	0.005	0.007
D	0.95	1.05	0.037	0.041
E	0.55	0.65	0.022	0.026
E1	0.15	0.25	0.006	0.010
e	0.65 BSC		0.026 BSC	
L	0.20	0.30	0.008	0.012
L1	0.05 REF		0.002 REF	





NOTE:



Dimensions are exclusive of Burrs, Mold Flash and Tie Bar extrusions.

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